

PTDH40120BY

1200V 40A Si IGBT Discrete

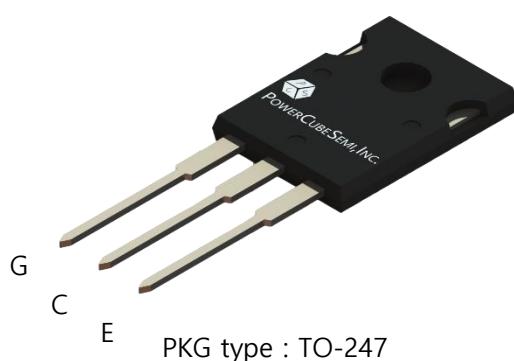


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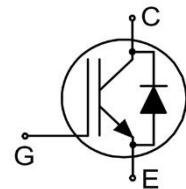
Features

Si IGBT Discrete

- Rated to 1200V at 40Amps @ $T_J = 25^\circ\text{C}$
- $V_{CE(\text{sat})} = 1.70\text{V}$ @ $I_C = 40\text{A}$
- High breakdown voltage to 1200V for improved reliability
- Maximum Junction Temperature 175°C
- Positive temperature coefficient
- Including fast & soft recovery ant-parallel FWD
- High short circuit capability (10us)



PKG type : TO-247



Absolute Maximum Ratings

Symbol	Parameter		Value	Unit
BV_{CES}	Collector-Emitter Breakdown Voltage		1200	V
I_C	DC Collector Current	$T_C = 25^\circ\text{C}$	80	A
		$T_C = 100^\circ\text{C}$	40	
$I_{C, \text{Pulse}}$	Pulsed Collector Current		160	A
I_F	Diode Forward Current	$T_C = 25^\circ\text{C}$	80	A
		$T_C = 100^\circ\text{C}$	40	
$I_{F, \text{Pulse}}$	Diode Pulsed Current		160	A
V_{GE}	Continuous Gate-Emitter Voltage		± 20	V
V_{GE}	Transient Gate-Emitter Voltage		± 30	
P_D	Power Dissipation	$T_C = 25^\circ\text{C}$	375	W
t_{SC}	Short circuit withstand time		10	μs
T_{vj}	Operating Junction Temperature Range		-40 to 175°C	$^\circ\text{C}$
T_{stg}	Storage Temperature Range		-55 to 150°C	



Package Marking and Ordering Information

Device Marking	Device	Package	Packing Method	Tape width	Quantity
PTDH40120BY	PTDH40120	TO-247	TUBE	-	30

Electrical Characteristics

$T_j=25^\circ\text{C}$ Unless Otherwise Specified

Static Characteristics

Symbol	Parameter	Test Condition	Numerical			Unit
			Min	Typ	Max	
BV_{CES}	Collector-Emitter Breakdown Voltage	$I_C=250\mu\text{A}, V_{\text{GE}}=0\text{V}$	1200	-	-	V
$V_{\text{CE}(\text{sat})}$	Collector-Emitter Saturation Voltage	$I_C=40\text{A}, V_{\text{GE}}=15\text{V}$	$T_j=25^\circ\text{C}$	-	1.70	2.00
			$T_j=125^\circ\text{C}$	-	1.95	-
			$T_j=150^\circ\text{C}$	-	2.05	-
$V_{\text{GE}(\text{TH})}$	Gate-Emitter Threshold Voltage	$V_{\text{CE}}=V_{\text{GE}}, I_C=1.4\text{mA}$	5.2	5.8	6.5	V
I_{CES}	Zero Gate Voltage Collector Current	$V_{\text{CE}}=1200\text{V}, V_{\text{GE}}=0\text{V}$	$T_j=25^\circ\text{C}$	-	-	0.25
			$T_j=150^\circ\text{C}$	-	-	4.00
I_{GES}	Gate-Emitter Leakage Current	$V_{\text{GE}}=\pm 20\text{V}, V_{\text{CE}}=0\text{V}$	-	-	100	nA

Dynamic Characteristics

Symbol	Parameter	Test Condition	Numerical			Unit
			Min	Typ	Max	
Q_G	Total Gate Charge	$V_{\text{CC}}=600\text{V}, I_C=40\text{A}, V_{\text{GE}}=15\text{V}$	-	0.26	-	uC
V_F	Diode Forward Voltage	$I_F=40\text{A}$	$T_j=25^\circ\text{C}$	-	2.00	2.50
			$T_j=125^\circ\text{C}$	-	1.80	-
			$T_j=150^\circ\text{C}$	-	1.70	-
C_{IES}	Input Capacitance	$V_{\text{CE}}=25\text{V}, V_{\text{GE}}=0\text{V}, f=1\text{MHz}$	-	5.47	-	nF
C_{RES}	Reverse Transfer Capacitance		-	0.05	-	



Electrical Characteristics

T_j=25°C Unless Otherwise Specified

Switching Characteristics

Symbol	Parameter	Test Condition	Numerical			Unit
			Min	Typ	Max	
t _{d(on)}	Turn-On Delay Time	V _{GE} =-5~15V, V _{CC} =600V, I _C =40A, R _G =20Ω	T _j =25°C	-	23	-
t _r	Turn-On Rise Time			-	25	-
t _{d(off)}	Turn-Off Delay Time			-	26	-
t _f	Turn-Off Fall Time		T _j =125°C	-	75	-
E _{on}	Turn-On Switching Energy			-	73	-
E _{off}	Turn-Off Switching Energy			-	69	-
E _{rec}	Reverse Recovery Energy		T _j =150°C	-	267	-
I _{rr}	Reverse Recovery Current			-	298	-
Q _{rr}	Reverse Recovery Charge			-	321	-
T _{rr}	Reverse Recovery Time			-	175	-
				-	262	-
				-	315	-
				-	4.2	-
				-	4.3	-
				-	4.4	-
				-	2.1	-
				-	3.5	-
				-	3.9	-
				-	1.2	-
				-	2.9	-
				-	3.6	-
				-	16	-
				-	19	-
				-	23	-
				-	3.23	-
				-	7.41	-
				-	8.95	-
				-	524	-
				-	825	-
				-	938	-
				-	ns	

Thermal Characteristics

Symbol	Parameter	Numerical	Unit
R _{θ(J-A)}	Thermal Resistance Junction-to-Ambient	40	K/W
R _{θ(J-C)}	Thermal Resistance Junction-to-Case for IGBT	0.40	
R _{θ(J-C)}	Thermal Resistance Junction-to-Case for Diode	0.65	

Typical Characteristics

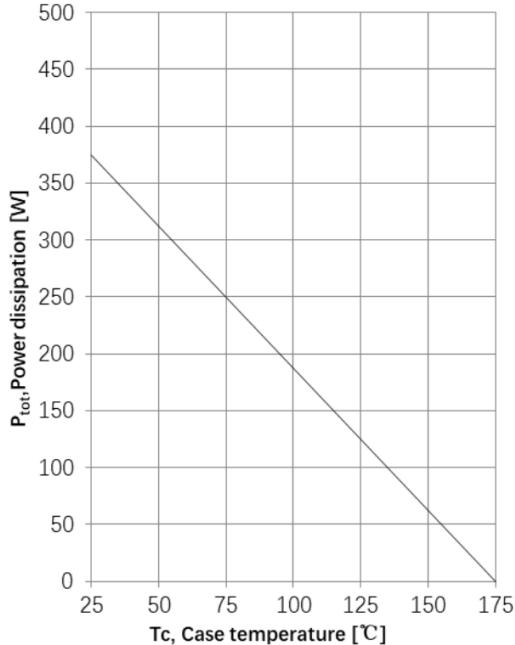


Figure 1. Power dissipation as a function of case temperature ($T_J \leq 175^\circ\text{C}$)

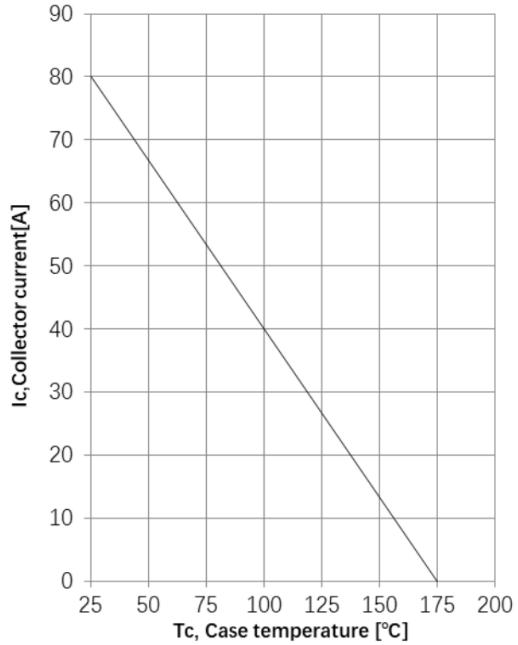


Figure 2. Collector current as a function of case temperature ($V_{GE} \geq 15\text{V}$, $T_J \leq 175^\circ\text{C}$)

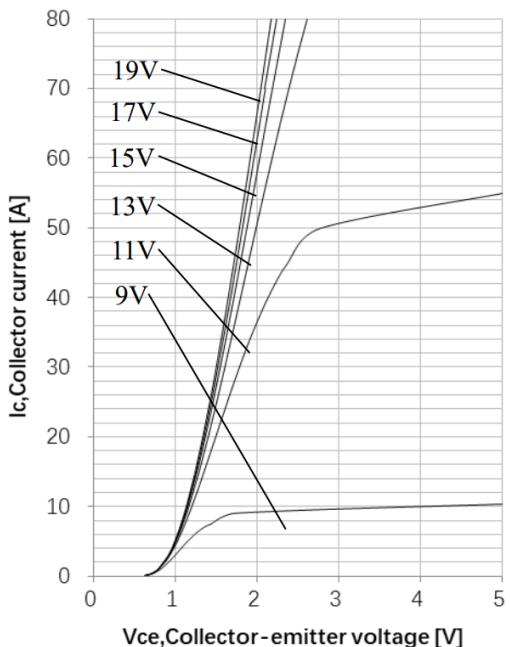


Figure 3. Output Characteristics ($T_J = 25^\circ\text{C}$)

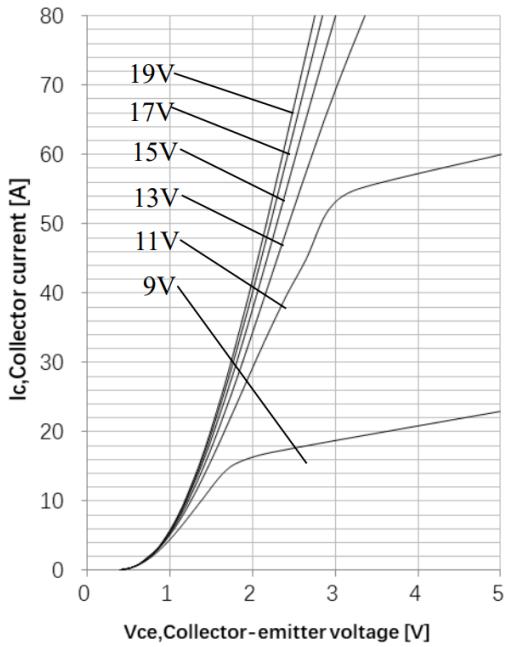


Figure 4. Output Characteristics ($T_J = 150^\circ\text{C}$)

Typical Characteristics

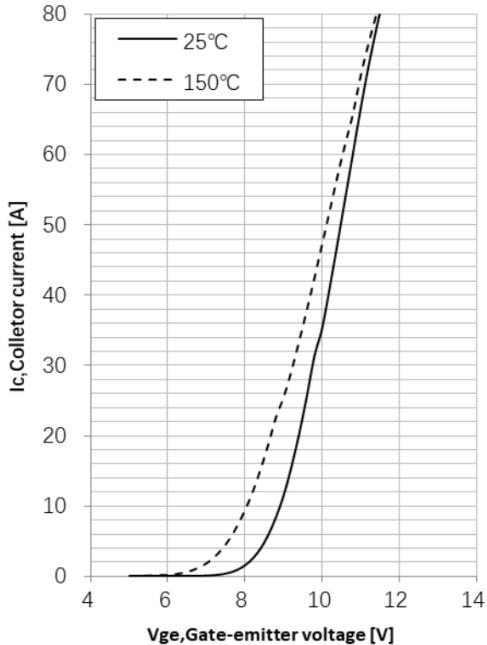


Figure 5. Typical transfer characteristic ($V_{CE}=20\text{V}$)

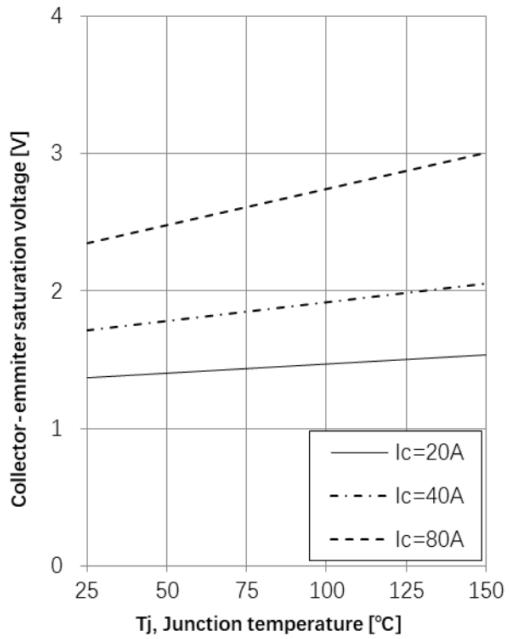


Figure 6. Typical collector-Emitter saturation voltage as a function of junction temperature

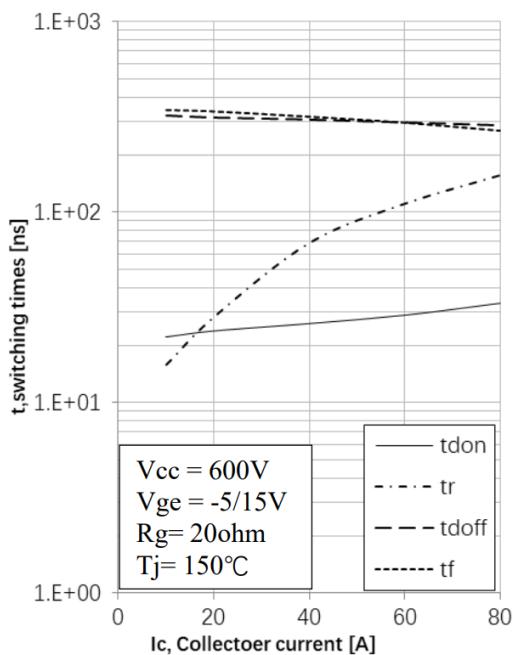


Figure 7. Typical Switching time as a function of collector current

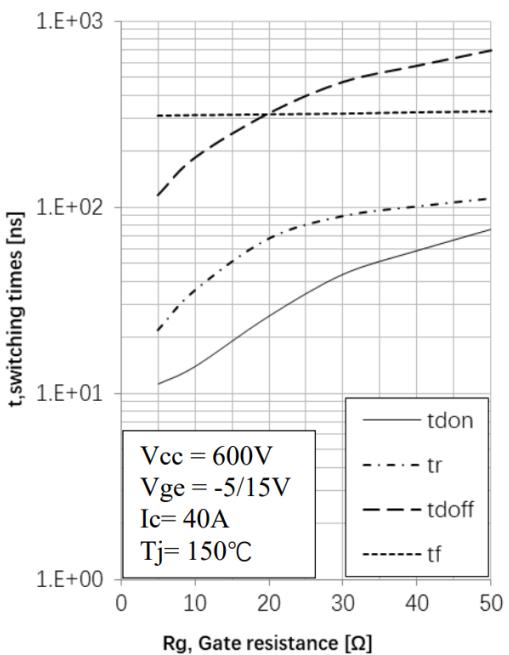


Figure 8. Typical Switching times as a function of gate resistance

Typical Characteristics

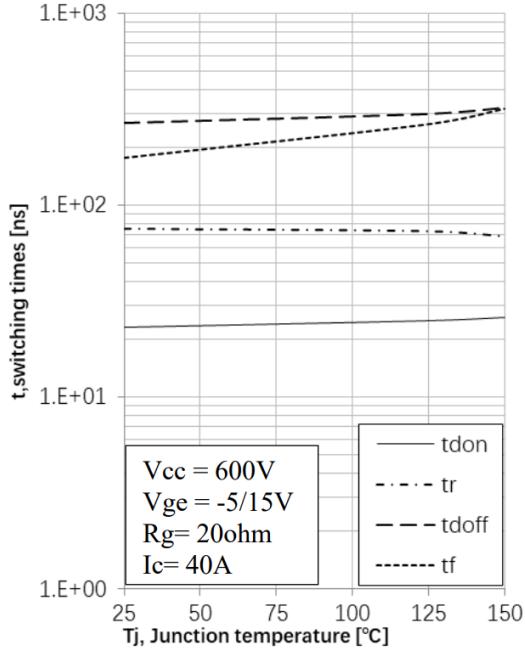


Figure 9. Typical Switching times as a function of junction temperature

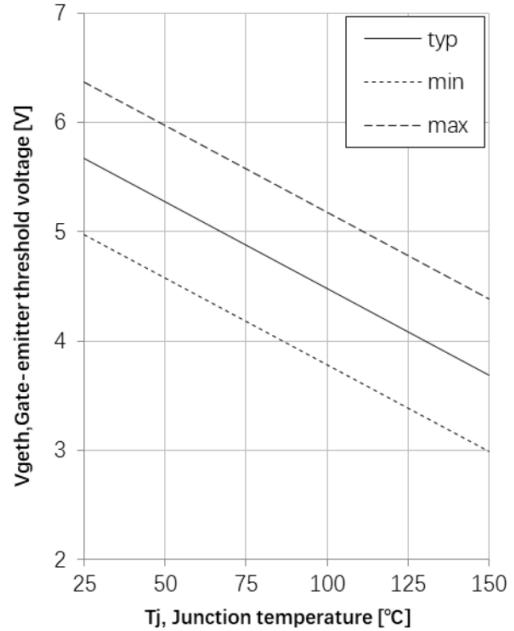


Figure 10. Gate-Emitter threshold voltage as a function of junction temperature

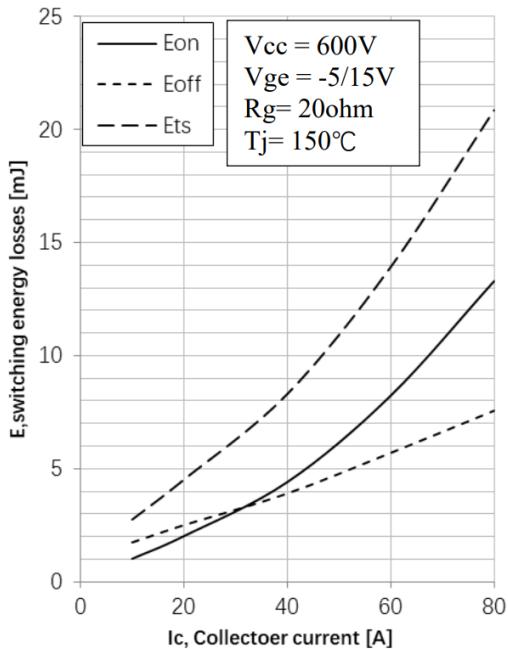


Figure 11. Typical Switching Energy losses as a function of collector current

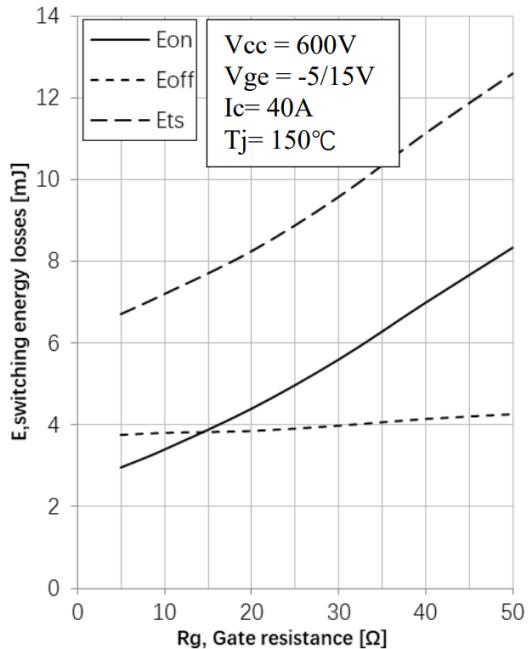


Figure 12. Typical Switching Energy losses as a function of gate resistance

Typical Characteristics

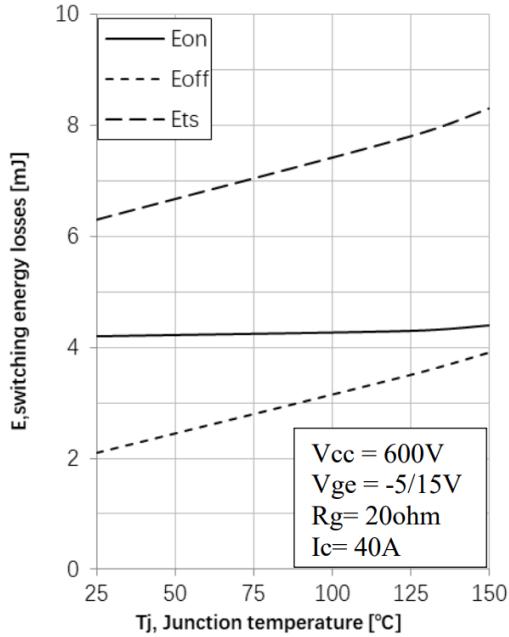


Figure 13. Typical Switching Energy losses as a function of junction temperature

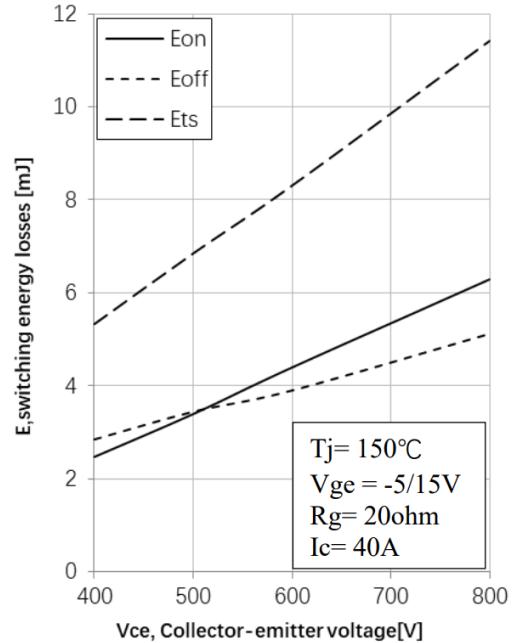


Figure 14. Typical Switching Energy losses as a function of collector-emitter voltage

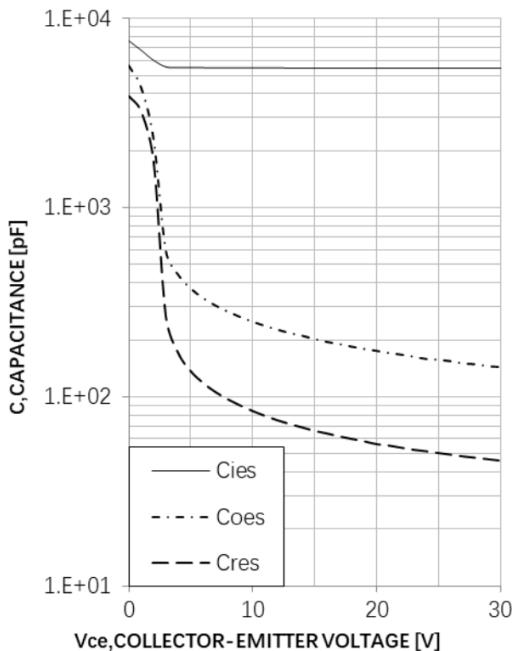


Figure 15. Typical capacitance as a function of collector-emitter voltage

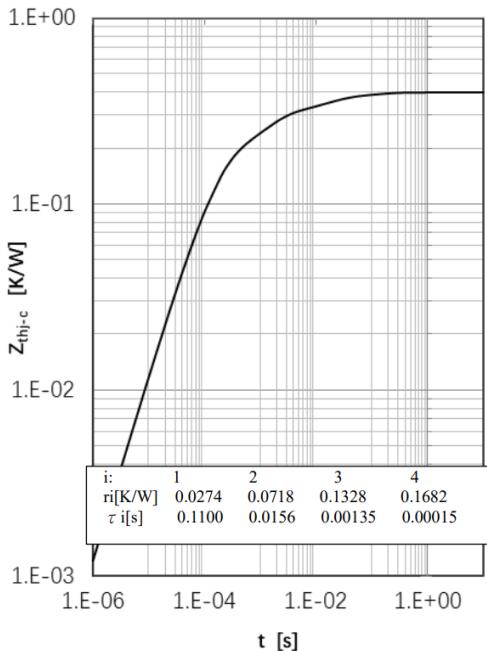


Figure 16. IGBT Transient Thermal Impedance

Typical Characteristics

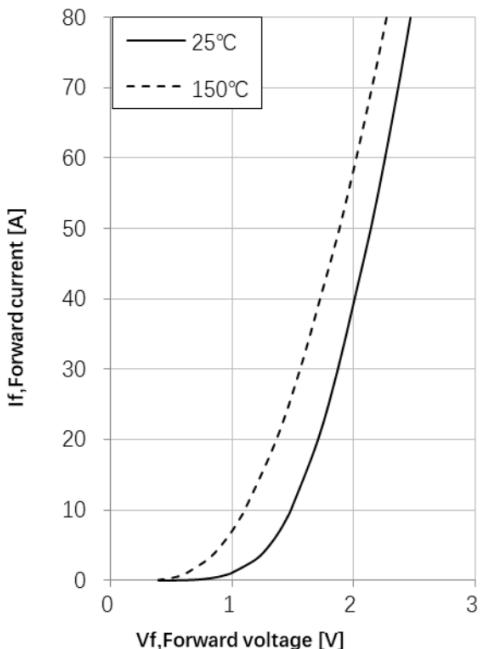
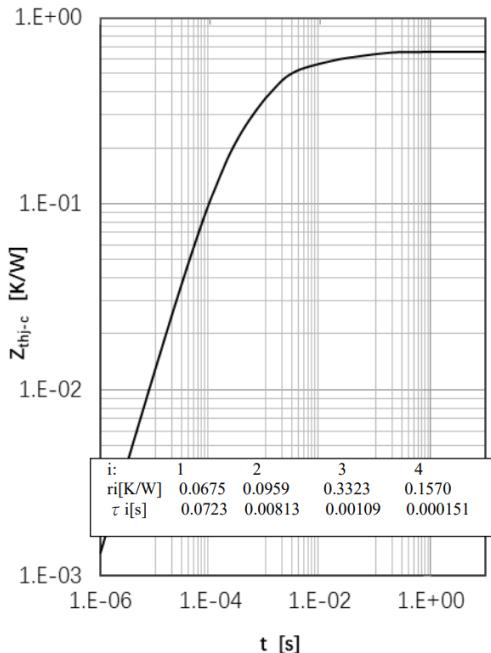


Figure 17. Diode Transient Thermal Impedance

Figure 18. Diode forward current as a function of forward voltage

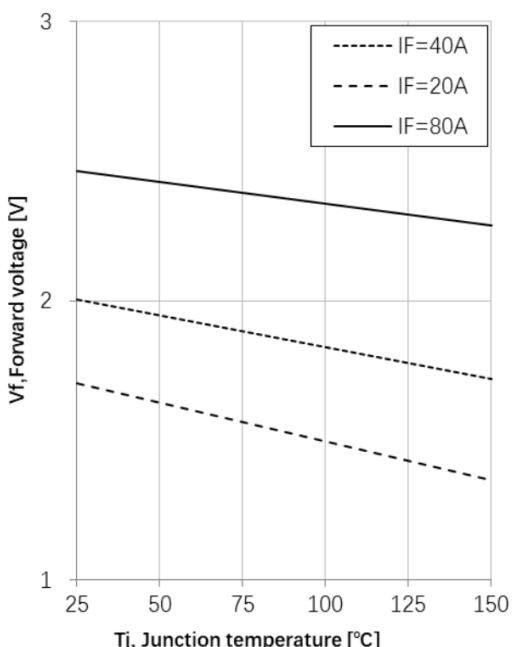
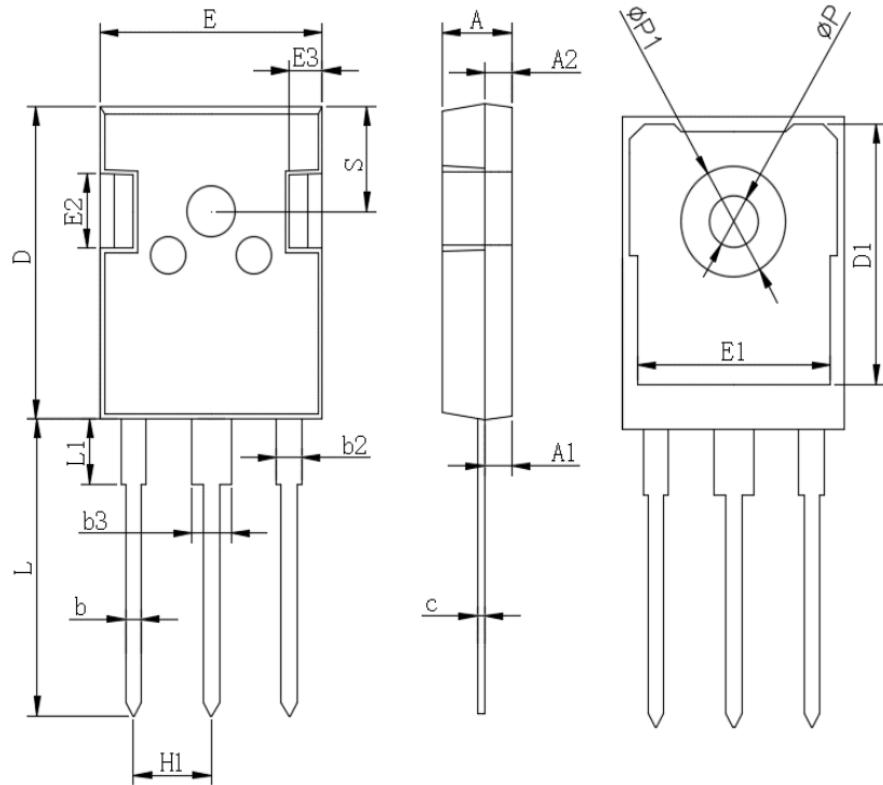


Figure 19. Diode forward voltage as a function of junction temperature



Package Outline



Unit : mm

SYMBOL	DIMENSIONS	
	MIN	MAX
A	4.80	5.20
A1	2.21	2.61
A2	1.85	2.15
b	1.0	1.4
b2	1.91	2.21
C	0.5	0.7
D	20.70	21.30
D1	16.25	16.85
E	15.50	16.10
E1	13.0	13.6
E2	4.80	5.20
E3	2.30	2.70
L	19.62	20.22
L1	-	4.30
ΦP	3.40	3.80
ΦP1	-	7.30
S	6.15 Typ	
H1	5.44 Typ	
b3	2.80	3.20